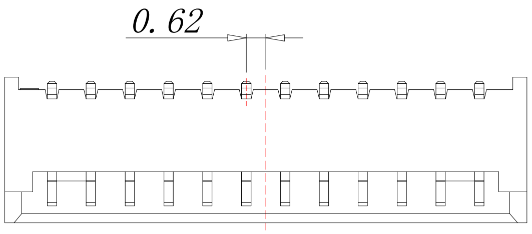
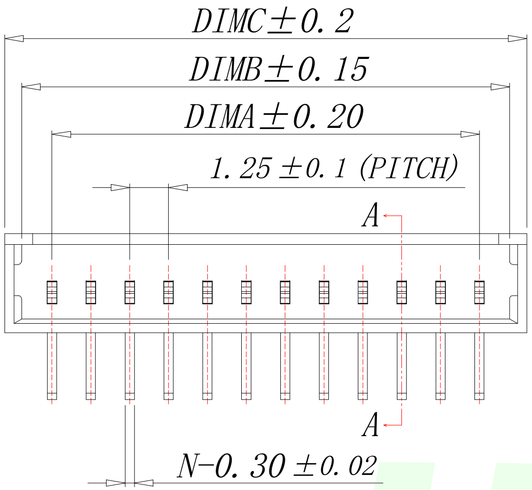
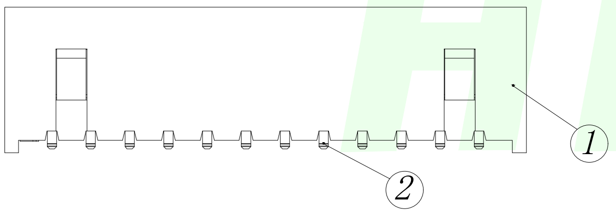
RoHs

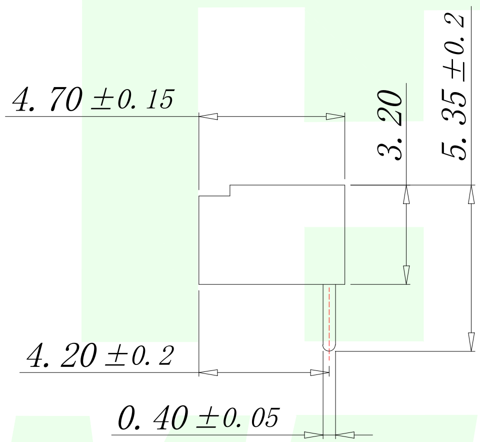


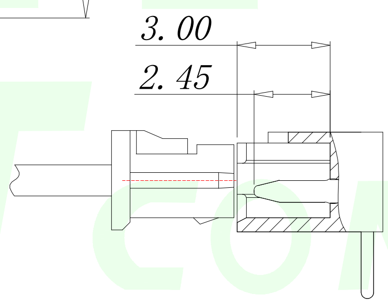




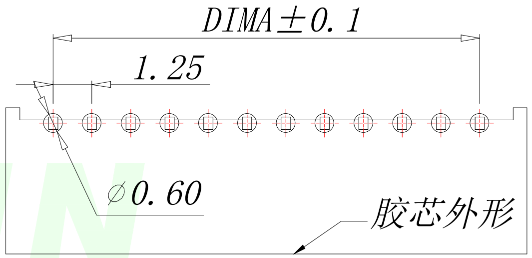
Technical Index:

1. The surface of the plastic parts should be smooth, no rough edges, no obvious shrinkage, defects, cracks and other phenomena)
2. Lock Configuration: 2 to 3Pin is 1, ≥4Pin is 2
3. Temperature range: -25° C~+85° C.
4. Rated voltage: 125V, AC/DC.
5. Contact resistance: ≤0.02Ω.
6. Insulation resistance: ≥100MΩ





SECTION A-A

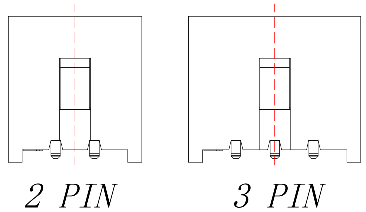


适用线路板(PCB LAYOUT)

VER	MARK	PR. BY	DESCRIPTTON	DATE

Part No	Pin	A	B	C
W1251100-2PR2123	2	1.25	3.20	4.30
W1251100-3PR2123	3	2.50	4.45	5.55
W1251100-4PR2123	4	3.75	5.70	6.80
W1251100-5PR2123	5	5.00	6.95	8.05
W1251100-6PR2123	6	6.25	8.20	9.30
W1251100-7PR2123	7	7.50	9.45	10.55
W1251100-8PR2123	8	8.75	10.70	11.80
W1251100-9PR2123	9	10.00	11.95	13.05
W1251100-10PR2123	10	11.25	13.20	14.30
W1251100-11PR2123	11	12.50	14.45	15.55
W1251100-12PR2123	12	13.75	15.70	16.80
W1251100-13PR2123	13	15.00	16.95	18.05
W1251100-14PR2123	14	16.25	18.20	19.30
W1251100-15PR2123	15	17.50	19.45	20.55
W1251100-16PR2123	16	18.75	20.70	21.80
W1251100-17PR2123	17	20.00	21.95	23.05
W1251100-18PR2123	18	21.25	23.20	24.30
W1251100-19PR2123	19	22.50	24.45	25.55
W1251100-20PR2123	20	23.75	25.70	26.80

序号	品名	材质
1	1.25 Pitch R/A Wire To Board Housing DIP(H=3.2)	PA66 UL94V-2 Red
2	1.25 Pitch R/A Wire To Board Terminal DIP(H=3.2)	Copper Alloy/ Tin Plating



LOCK CONFIGURATION(锁扣位置)

GENERAL TOLERANCES UNLESS SPECIFIED		深圳市华明通电子有限公司 HMTCONN Shenzhen Huamingtong Electronics Co., Ltd	
X.° ±0.50	X.° ±5°	PART NO. W1251100-XPR2123	TITLE: 1.25 PITCH H3.2 R/A WIRE TO BOARD DIP CONN.
X.X° ±0.20	X.X° ±3°	DESIGN: James	CUSTOMER / SIZE: A4 / UNITS: MM
X.XX° ±0.10	X.XX° ±1°	CHED: Talen	SCALE: N:A / SHEET: 1/1
MANUFACTURE DWG		APPD: Sophia	